

*fee  
incl*PATENT APPLICATION  
Attorney Docket: 54364IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gupta, et al.

Serial No.: 09/847,667

Filed: 5/1/2001

For: Method for Bonding Wafers to  
Produce Stacked Integrated  
Circuits

Group Art Unit: 2827

Examiner: James Mitchell

PETITION FOR EXTENSION OF TIMECommissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450RECEIVED  
CENTRAL FAX CENTER

APR - 1 2004

OFFICIAL

Sir:

Applicant hereby petitions the Commissioner of Patents and Trademarks under 37 C.F.R. Sect. 1.136(a) to extend the time for response to the Office Action dated 12/4/2003 by 1 month.

The Commissioner is hereby authorized to charge all fees which may be required in this application under 37 C.F.R. Sect. 1.16-1.17 during its entire pendency, or credit any overpayment, to Deposit Account No. 23-0424. This petition is filed in duplicate.

I hereby certify that this paper is being transmitted via facsimile to: 703-872-9306

Respectfully submitted,

Calvin B. Ward  
Registration No. 30,896

Dated: April 1, 2004

18 Crow Canyon Court, Suite 305  
San Ramon, CA 94583  
Telephone (925) 855-0413  
Telefax (925)855-921404/08/2004 PBX/FAX VERSA 2004.1 04/08/2004  
01-FE:2251 55.00 JA